

<b>PCN Number:</b>	20201204001.1	<b>PCN Date:</b>	Mar 10, 2021
<b>Title:</b>	Qualification of TI Malaysia (TIM) as an additional Assembly & Test site for select devices		
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	June 10, 2021	<b>Estimated Sample Availability:</b>	Date Provided at Sample request
<b>Change Type:</b>			
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input checked="" type="checkbox"/>	Test Site
<input checked="" type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

**PCN Details**

**Description of Change:**

Texas Instruments Incorporated is announcing the qualification TI Malaysia (TIM) as Additional Assembly & test Site for select devices listed in the "Product Affected" Section. No material differences between sites.

Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City
TI Taiwan	TAI	TWN	Chung Ho, New Taipei City
<a href="#">TI Malaysia</a>	<a href="#">MLA</a>	<a href="#">MYS</a>	<a href="#">Kuala Lumpur</a>

Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.

**Reason for Change:**

Continuity of supply

**Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):**

None

**Anticipated impact on Material Declaration**

<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below <a href="http://www.ti.com/quality/docs/materialcontentsearch.tsp">http://www.ti.com/quality/docs/materialcontentsearch.tsp</a>
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**Changes to product identification resulting from this PCN:**

Assembly Site		
TI-Taiwan	Assembly Site Origin (22L)	ASO: TAI
<a href="#">TI Malaysia</a>	<a href="#">Assembly Site Origin (22L)</a>	<a href="#">ASO: MLA</a>

Sample product shipping label (not actual product label)



MADE IN: Malaysia  
2DC: 2Q:

MSL 2 / 260C / 1 YEAR	SEAL DT
MSL 1 / 235C / UNLIM	03/29/04

OPT:  
ITEM: 39  
LBL: 5A (L) TO: 1750





(1P) SN74LS07NSR  
(Q) 2000 (D) 0336  
(31T) LOT: 3959047MLA  
(4W) TKY (1T) 7523483SI2  
(P)  
(2P) REV: (V) 0033317  
(20L) CSO: SHE (21L) CCO: USA  
(22L) ASO: MLA (23L) ACO: MYS



**Product Affected:**

UCC21520ADW	UCC21520ADWR	UCC21520DW	UCC21520DWR
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## Qualification Report

Approved Date 05-Mar-2021

### Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: <u>UCC21520ADW</u>	QBS Product Reference: <u>UCC21520ADWR</u>	QBS Product & Package Reference: <u>UCC21520AQDWRQ1</u>
AC	Autoclave 121C	96 Hours	3/231/0	3/231/0	3/231/0
CDM	ESD - CDM	1500 V	1/3/0	-	-
CDM	ESD - CDM - Q100	1500 V	-	-	1/3/0
ED	Auto Electrical Distributions	Cpk>1.67 Room, hot, and cold test	-	-	3/90/0
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	3/231/0	3/231/0	3/231/0
HBM	ESD - HBM	4000 V	1/3/0	-	-
HTOL	Life Test, 125C	1000 Hours	1/77/0	1/77/0	1/77/0
HTSL	High Temp Storage Bake 170C	420 Hours	-	3/231/0	-
HTSL	High Temp Storage Bake 175C	500 Hours	3/135/0	-	3/135/0
TC	Temperature Cycle, -65/150C	500 Hours	3/231/0	3/231/0	3/231/0
YLD	FTY and Bin Summary	-	3/Pass	-	-

- QBS: Qual By Similarity

- Qual Device UCC21520ADW is qualified at LEVEL3-260C

- Device UCC21520ADW contains multiple dies.

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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